

**Features**

- Low Forward Voltage Drop
- Fast Switching
- Ultra-Small Leadless Surface Mount Package
- PN Junction Guard Ring for Transient and ESD Protection
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

**Mechanical Data**

- Case: X1-DFN1006-2
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: Cathode Bar
- Terminals: Finish - NiPdAu Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (e4)
- Weight: 0.001 grams (Approximate)

X1-DFN1006-2



Top View



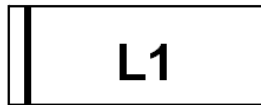
Bottom View

**Ordering Information** (Note 4)

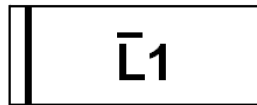
Part Number	Case	Packaging
BAT54LP-7	X1-DFN1006-2	3,000/Tape & Reel
BAT54LP-7B	X1-DFN1006-2	10,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
  2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

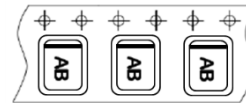
**Marking Information**



Top View



Top View



Bar Denotes Cathode Side

L1 or  $\bar{L}1$  = Product Type Marking Code  
 Bar Denotes Cathode Side

**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>	30	V
Working Peak Reverse Voltage	V <sub>RWM</sub>		
DC Blocking Voltage	V <sub>R</sub>		
Forward Continuous Current	I <sub>F</sub>	200	mA
Repetitive Peak Forward Current	I <sub>FRM</sub>	300	mA
Forward Surge Current @ t < 1.0s	I <sub>FSM</sub>	600	mA

**Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P <sub>D</sub>	250	mW
Thermal Resistance, Junction to Ambient Air (Note 5)	R <sub>θJA</sub>	400	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +125	°C

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	V <sub>(BR)R</sub>	30	—	—	V	I <sub>R</sub> = 100µA
Forward Voltage	V <sub>F</sub>	—	—	240 320 400 500 1,000	mV	I <sub>F</sub> = 0.1mA I <sub>F</sub> = 1mA I <sub>F</sub> = 10mA I <sub>F</sub> = 30mA I <sub>F</sub> = 100mA
Reverse Leakage Current (Note 6)	I <sub>R</sub>	—	—	2.0	µA	V <sub>R</sub> = 25V
Total Capacitance	C <sub>T</sub>	—	—	10	pF	V <sub>R</sub> = 1.0V, f = 1.0MHz
Reverse Recovery Time	t <sub>RR</sub>	—	—	5.0	ns	I <sub>F</sub> = 10mA through I <sub>R</sub> = 10mA to I <sub>R</sub> = 1.0mA, R <sub>L</sub> = 100Ω

Notes: 5. Part mounted on FR-4 PC board with recommended pad layout, which can be found on our website at <http://www.diodes.com/package-outlines.html>.  
6. Short duration pulse test used to minimize self-heating effect.

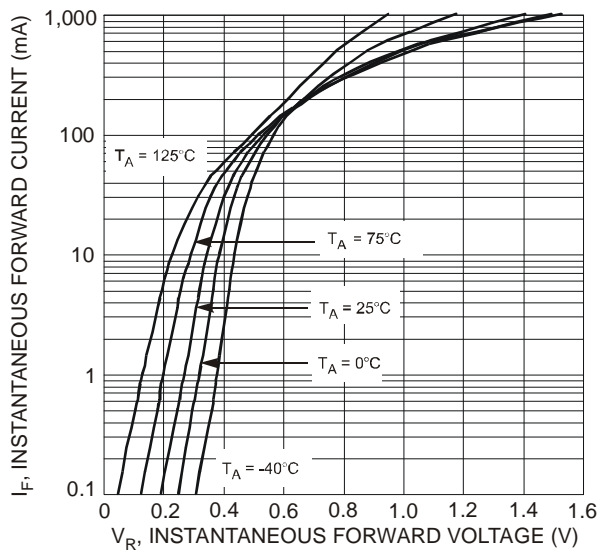


Fig. 1 Typical Forward Characteristics

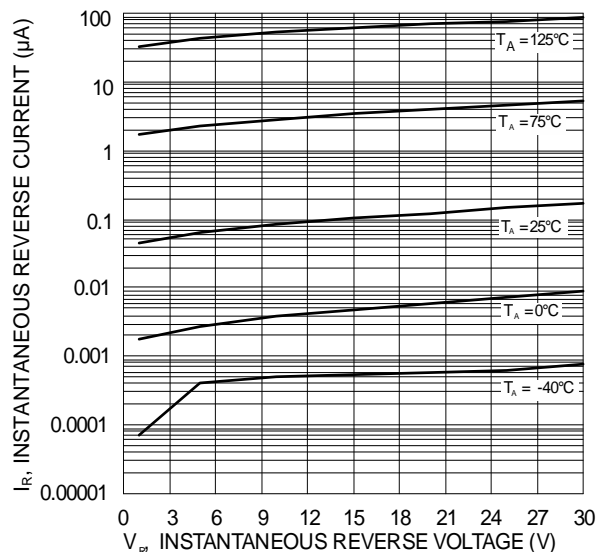


Fig. 2 Typical Reverse Characteristics

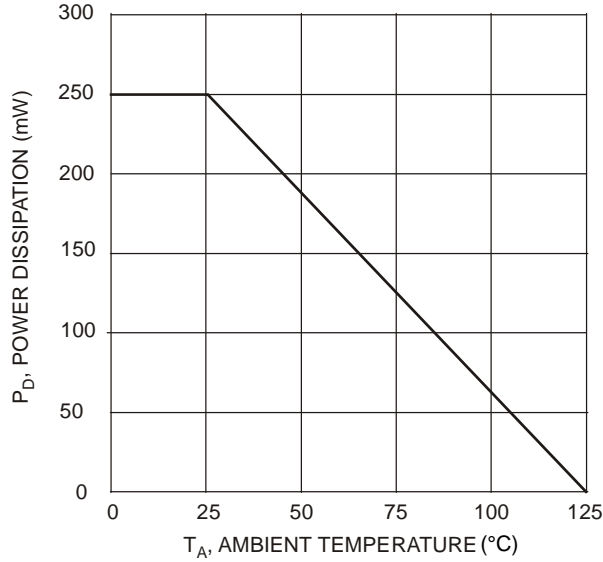
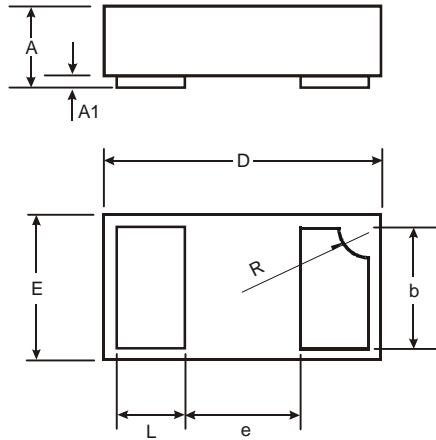


Fig. 3 Power Derating Curve

### Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

#### X1-DFN1006-2

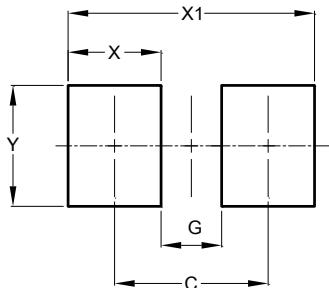


X1-DFN1006-2			
Dim	Min	Max	Typ
A	0.47	0.53	0.50
A1	0	0.05	0.03
b	0.45	0.55	0.50
D	0.95	1.075	1.00
E	0.55	0.675	0.60
e	-	-	0.40
L	0.20	0.30	0.25
R	0.05	0.15	0.10
<b>All Dimensions in mm</b>			

### Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

#### X1-DFN1006-2



Dimensions	Value (in mm)
C	0.70
G	0.30
X	0.40
X1	1.10
Y	0.70

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